DATA SHEET



MOS FIELD EFFECT TRANSISTOR 2SK3305

SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

DESCRIPTION

The 2SK3305 is N-Channel DMOS FET device that features a low gate charge and excellent switching characteristics, and designed for high voltage applications such as switching power supply, AC adapter.

FEATURES

- Low gate charge: $Q{\rm G}$ = 13 nC TYP. (VDD = 400 V, VGS = 10 V, ID = 5.0 A)
- Gate voltage rating: ±30 V
- Low on-state resistance
- RDS(on) = 1.5 Ω MAX. (VGs = 10 V, ID = 2.5 A)
- Avalanche capability ratings

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C)

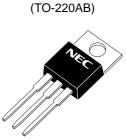
Drain to Source Voltage (Vgs = 0 V)	Vdss	500	V
Gate to Source Voltage (VDS = 0 V)	VGSS(AC)	±30	V
Drain Current (DC)	D(DC)	±5	А
Drain Current (pulse) ^{Note1}	D(pulse)	±20	Α
Total Power Dissipation (Tc = 25°C)	Р⊤	75	W
Total Power Dissipation (T _A = 25°C)	Рт	1.5	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	–55 to +150	°C
Single Avalanche Current Note2	AS	5.0	А
Single Avalanche Energy Note2	Eas	125	mJ

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1 %

2. Starting T_{ch} = 25 °C, V_{DD} = 150 V, R_G = 25 Ω , V_{GS} = 20 V \rightarrow 0 V

ORDERING INFORMATION

PART NUMBER	PACKAGE		
2SK3305	TO-220AB		
2SK3305-S	TO-262		
2SK3305-ZJ	TO-263		











The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version. Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

Document No. D14003EJ1V0DS00 (1st edition) Date Published March 2000 NS CP(K) Printed in Japan

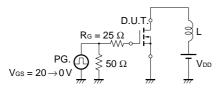
© NEC Corporation 1998,2000

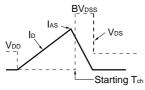
查迴:2% (24/5 c) 供你的 RISTICS (TA = 25 °C)

NEC

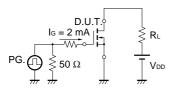
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain Leakage Current	IDSS	Vds = 500 V, Vgs = 0 V			100	μA
Gate to Source Leakage Current	lgss	$V_{GS} = \pm 30 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$			±100	nA
Gate to Source Cut-off Voltage	VGS(off)	V _{DS} = 10 V, I _D = 1 mA	2.5		3.5	V
Forward Transfer Admittance	y _{fs}	Vps = 10 V, Ip = 2.5 A	1.0	3.0		S
Drain to Source On-state Resistance	RDS(on)	V _{GS} = 10 V, I _D = 2.5 A		1.3	1.5	Ω
Input Capacitance	Ciss	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		700		pF
Output Capacitance	Coss			115		pF
Reverse Transfer Capacitance	Crss			6		pF
Turn-on Delay Time	td(on)	$V_{DD} = 150 \text{ V}, \text{ ID} = 2.5 \text{ A}, \text{ V}_{GS(on)} = 10 \text{ V},$		16		ns
Rise Time	tr	$R_G = 10 \Omega$, $R_L = 60 \Omega$		3		ns
Turn-off Delay Time	td(off)			33		ns
Fall Time	tr			5.5		ns
Total Gate Charge	QG	$V_{DD} = 400 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 5.0 \text{ A}$		13		nC
Gate to Source Charge	Q _{GS}			4		nC
Gate to Drain Charge	Q _{GD}			4.5		nC
Body Diode Forward Voltage	VF(S-D)	IF = 5.0 A, VGS = 0 V		0.9		V
Reverse Recovery Time	trr	$I_F = 5.0 \text{ A}, \text{ V}_{GS} = 0 \text{ V}, \text{ di/dt} = 50 \text{ A}/\mu\text{s}$		0.6		μs
Reverse Recovery Charge	Qrr			3.3		μC

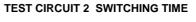
TEST CIRCUIT 1 AVALANCHE CAPABILITY

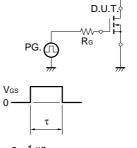




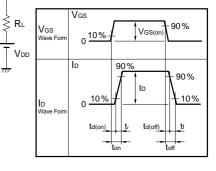
TEST CIRCUIT 3 GATE CHARGE



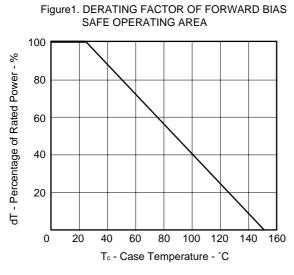


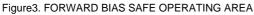


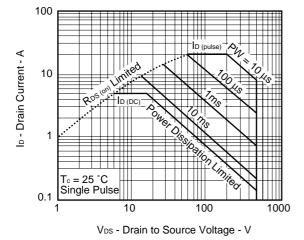


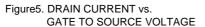


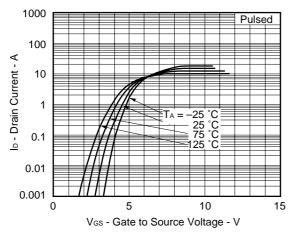
查询问 CAL CHARA 供 ERTS TICS (TA = 25°C)

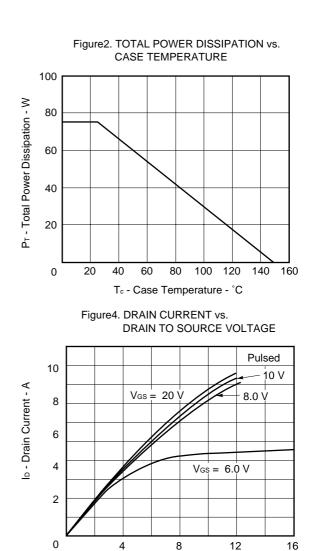












VDS - Drain to Source Voltage - V

查询"2SK3305-S"供应商

NEC

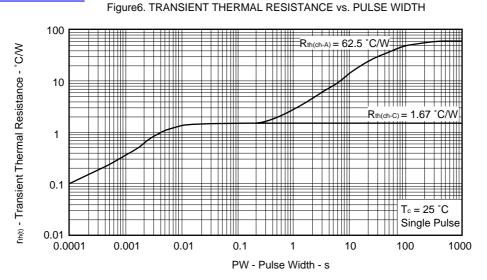
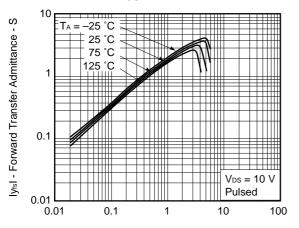


Figure7. FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



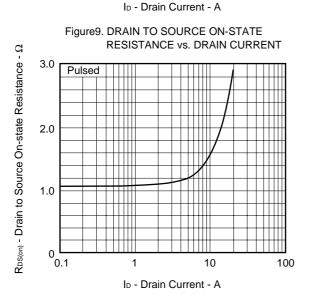


Figure8. DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

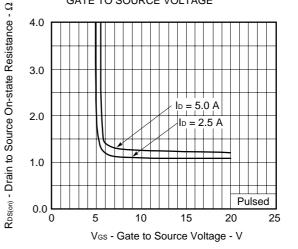
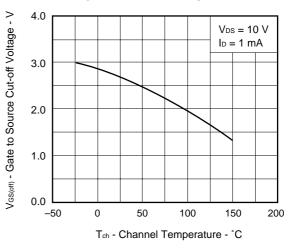


Figure10. GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



Pulsed

查询"2\$K3305-\$"供应商

NEC

1000

800

600 400

200

0

0.1

1

10

IF - Drain Current - A

ţ.

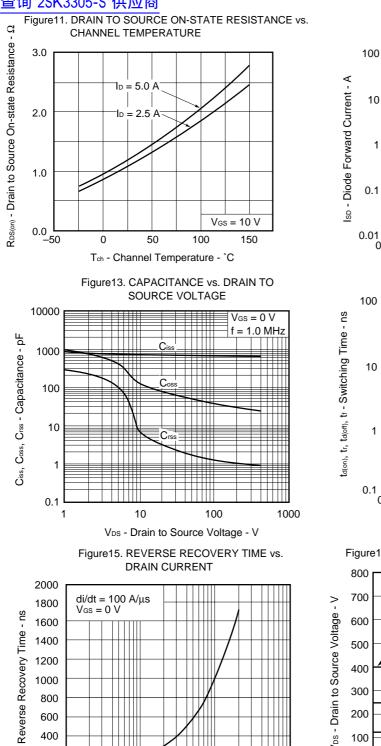


Figure12. SOURCE TO DRAIN DIODE FORWARD VOLTAGE

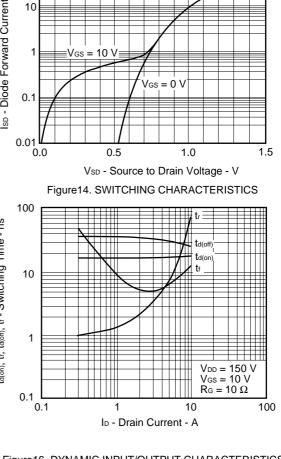
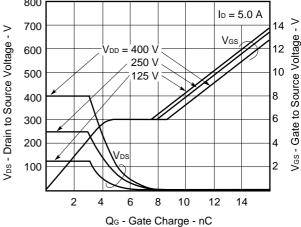


Figure16. DYNAMIC INPUT/OUTPUT CHARACTERISTICS



100

查询"2SK3305-S"供应商

NEC

Figure17. SINGLE AVALANCHE ENERGY vs STARTING CHANNEL TEMPERATURE

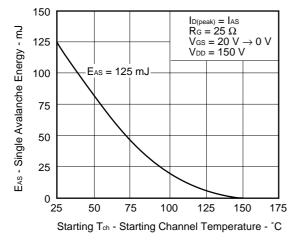
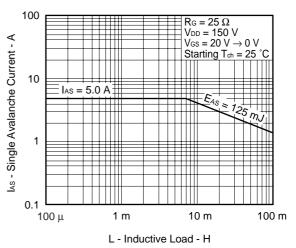
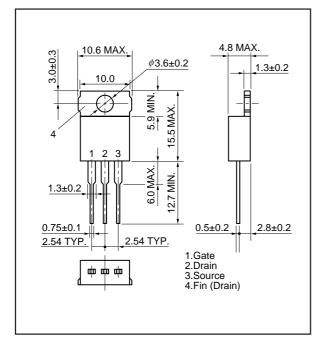


Figure 18. SINGLE AVALANCHE CURRENT vs INDUCTIVE LOAD

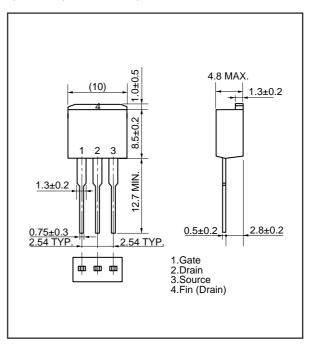


TATEKAGE DRAWINGS Unit: mm)

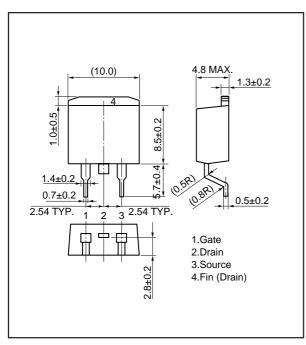
1) TO-220AB (MP-25)



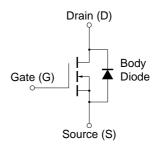
2) TO-262 (MP-25 Fin Cut)



3) TO-263 (MP-25ZJ)



EQUIVALENT CIRCUIT



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

查询"2SK3305-S"供应商

NEC

- The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.
- No part of this document may be copied or reproduced in any form or by any means without the prior written consent of NEC Corporation. NEC Corporation assumes no responsibility for any errors which may appear in this document.
- NEC Corporation does not assume any liability for infringement of patents, copyrights or other intellectual property
 rights of third parties by or arising from use of a device described herein or any other liability arising from use
 of such device. No license, either express, implied or otherwise, is granted under any patents, copyrights or other
 intellectual property rights of NEC Corporation or others.
- Descriptions of circuits, software, and other related information in this document are provided for illustrative purposes in semiconductor product operation and application examples. The incorporation of these circuits, software, and information in the design of the customer's equipment shall be done under the full responsibility of the customer. NEC Corporation assumes no responsibility for any losses incurred by the customer or third parties arising from the use of these circuits, software, and information.
- While NEC Corporation has been making continuous effort to enhance the reliability of its semiconductor devices, the possibility of defects cannot be eliminated entirely. To minimize risks of damage or injury to persons or property arising from a defect in an NEC semiconductor device, customers must incorporate sufficient safety measures in its design, such as redundancy, fire-containment, and anti-failure features.
- NEC devices are classified into the following three quality grades:
 "Standard", "Special", and "Specific". The Specific quality grade applies only to devices developed based on a customer designated "quality assurance program" for a specific application. The recommended applications of a device depend on its quality grade, as indicated below. Customers must check the quality grade of each device before using it in a particular application.
 - Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots
 - Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
 - Specific: Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

The quality grade of NEC devices is "Standard" unless otherwise specified in NEC's Data Sheets or Data Books. If customers intend to use NEC devices for applications other than those specified for Standard quality grade, they should contact an NEC sales representative in advance.